

RELIABILITY REPORT FOR MAX5389MAUD+

PLASTIC ENCAPSULATED DEVICES

June 5, 2013

MAXIM INTEGRATED

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Approved by
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Quality Assurance
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Conclusion

The MAX5389MAUD+ successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX5389 dual, 256-tap, volatile, low-voltage linear taper digital potentiometer offers three end-to-end resistance values of 10k, 50k, and 100k. Operating from a single +2.6V to +5.5V power supply, the device provides a low 35ppm/°C end-to-end temperature coefficient. The MAX5389 features an up/down interface. The small package size, low supply operating voltage, low supply current, and automotive temperature range of the MAX5389 make the device uniquely suited for the portable consumer market, battery backup industrial applications, and the automotive market. The MAX5389 is specified over the automotive -40°C to +125°C temperature range and is available in a 14-pin TSSOP package.



Dual, 256-Tap, Volatile, Low-Voltage Linear Taper Digital Potentiometer

II. Manufacturing Information

- A. Description/Function:
- B. Process:
- C. Number of Device Transistors:
- D. Fabrication Location:
- E. Assembly Location:
- F. Date of Initial Production:

III. Packaging Information

A Dealiana Turan	
A. Package Type:	14-pin 1550P
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3700
H. Flammability Rating:	Class UL94-V0
 Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C 	Level 1
J. Single Layer Theta Ja:	110°C/W
K. Single Layer Theta Jc:	30°C/W
L. Multi Layer Theta Ja:	100.4°C/W
M. Multi Layer Theta Jc:	30°C/W

S45

20059

California, Texas or Japan

January 22, 2010

Philippines, Thailand, or Malaysia

IV. Die Information

Α.	Dimensions:	62 X 71 mils
В.	Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C.	Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D.	Backside Metallization:	None
Ε.	Minimum Metal Width:	Metal1 = 0.5 microns (as drawn)
F.	Minimum Metal Spacing:	Metal1 = 0.45 microns (as drawn)
G.	Bondpad Dimensions:	
Н.	Isolation Dielectric:	SiO ₂
I.	Die Separation Method:	Wafer Saw



V. Quality Assurance Information

A.	Quality Assurance Contacts:	Richard Aburano (Manager, Reliability Engineering) Don Lipps (Manager, Reliability Engineering) Bryan Preeshl (Vice President of QA)
В.	Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet.0.1% For all Visual Defects.
C.	Observed Outgoing Defect Rate:	< 50 ppm
D.	Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \underbrace{1}_{\text{MTTF}} = \underbrace{1.83}_{192 \text{ x } 4340 \text{ x } 96 \text{ x } 2} \text{ (Chi square value for MTTF upper limit)}$$

$$\lambda = 11.4 \text{ x } 10^{-9}$$

𝔅 = 11.4 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maximintegrated.com/qa/reliability/monitor. Cumulative monitor data for the S45 Process results in a FIT Rate of 0.13 @ 25C and 2.31 @ 55C (0.8 eV, 60% UCL).

B. E.S.D. and Latch-Up Testing (lot SVZZCQ001E, D/C 0932)

The DP35-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250mA and overvoltage per JEDEC JESD78.



Table 1 Reliability Evaluation Test Results

MAX5389MAUD+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note	e 1)				
	Ta = 135°C	DC Parameters	48	0	SVZXCQ001A, D/C 0932
	Biased Time = 192 hrs.	& functionality	48	0	SVZYAQ001A, D/C 0912

Note 1: Life Test Data may represent plastic DIP qualification lots.